

## General Description

The Sanrise SRC70R900 is a high voltage power MOSFET, fabricated using advanced super junction technology. The resulting device has extremely low on resistance, low gate charge and fast switching time, making it especially suitable for applications which require superior power density and outstanding efficiency.

The SRC70R900 break down voltage is 700V and it has a high rugged avalanche characteristic.

The SRC70R900 is available in TO-220F, TO-252 packages.

## Features

- Ultra Low  $R_{DS(ON)} = 900m\Omega @ V_{GS} = 10V$ .
- Ultra Low Gate Charge,  $Q_g = 6.2nC$  typ.
- Fast switching capability
- Robust design with better EAS performance
- Non-automotive Qualified
- Ultra-fast body diode

## Application

- LED lighting
- Quick Charger

## Symbol

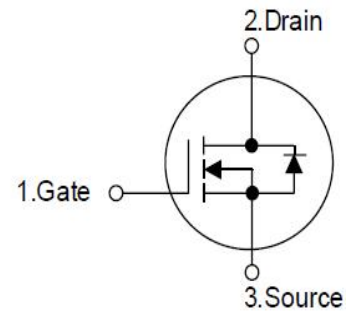
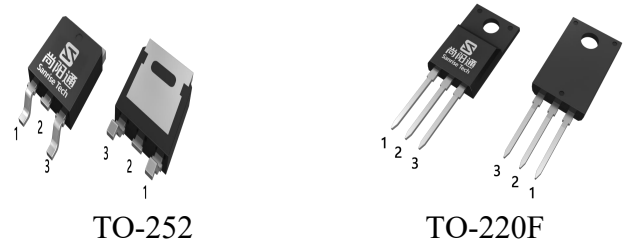


Figure 1 Symbol of SRC70R900

## Package Type

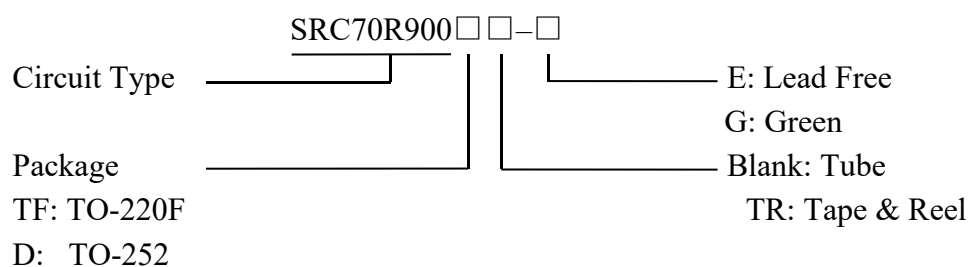


TO-252

TO-220F

Figure 2 Package Types of SRC70R900

## Ordering Information



Package	Part Number	Marking ID	Packing Type
TO-220F	SRC70R900TF-G	SRC70R900TFG	Tube
TO-252	SRC70R900DTR-G	SRC70R900DG	Tape & Reel

## Absolute Maximum Ratings

Parameter	Symbol	Rating	Unit
Drain-Source Voltage	$V_{DSS}$	700	V
Gate-Source Voltage (static)	$V_{GSS}$	±20	V
Gate-Source Voltage (dynamic), AC ( $f > 1$ Hz)	$V_{GSS}$	±30	V
Power Dissipation( $T_C=25^\circ\text{C}$ )	TO-220F	20	W
	TO-252	29	
Continuous Drain Current	$T_C=25^\circ\text{C}$	3.7	A
	$T_C=100^\circ\text{C}$	2.4	
	$T_C=125^\circ\text{C}$	1.7	
Pulsed Drain Current (Note 2)	$I_{DM}$	11.1	A
Avalanche Energy, Single Pulse (Note 3)	$E_{AS}$	75	mJ
Avalanche Energy, Repetitive (Note 2)	$E_{AR}$	0.1	mJ
Avalanche Current, Repetitive (Note 2)	$I_{AR}$	0.2	A
Continuous Diode Forward Current	$I_S$	3.7	A
Diode Pulse Current	$I_{S,PULSE}$	11.1	A
MOSFET dv/dt Ruggedness, $V_{DS} \leq 480\text{V}$	dv/dt	15	V/ns
Reverse Diode dv/dt, $V_{DS} \leq 480\text{V}$ , $I_{SD} \leq I_D$	dv/dt	50	V/ns
Operating Junction Temperature	$T_J$	150	$^\circ\text{C}$
Storage Temperature	$T_{STG}$	-55 to 150	$^\circ\text{C}$
Lead Temperature (Soldering, 10 sec)	$T_{LEAD}$	260	$^\circ\text{C}$

Note:

1. Absolute maximum ratings are those values beyond which the device could be permanently damaged. Absolute maximum ratings are stress ratings only and functional device operation is not implied.
2. Repetitive Rating: Pulse width limited by maximum junction temperature
3.  $I_{AS} = 3.0\text{A}$ ,  $V_{DD} = 60\text{V}$ ,  $R_G = 25\Omega$ , Starting  $T_J = 25^\circ\text{C}$

## Thermal Resistance

Parameter	Symbol	Min	Typ	Max	Unit
Thermal resistance, Junction-to-Case	TO-220F			6.0	$^\circ\text{C} / \text{W}$
	TO-252			4.2	
Thermal resistance, Junction-to-Ambient	TO-220F			80	$^\circ\text{C} / \text{W}$
	TO-252			62	

**Electrical Characteristics**
 $T_J = 25^\circ\text{C}$ , unless otherwise specified.

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
<b>Statistic Characteristics</b>						
Drain-Source Breakdown Voltage	$BV_{DSS}$	$V_{GS}=0V, I_D=250\mu A$	700			V
Zero Gate Voltage Drain Current	$I_{DSS}$	$V_{DS}=700V, V_{GS}=0V$			1	$\mu A$
Gate-Body Leakage Current	Forward	$I_{GSSF}, V_{GS}=20V, V_{DS}=0V$			100	nA
	Reverse	$I_{GSSR}, V_{GS}=-20V, V_{DS}=0V$			-100	
Gate Threshold Voltage	$V_{GS(TH)}$	$V_{DS}=V_{GS}, I_D=0.8mA$	2.5	3.5	4.5	V
Static Drain-Source On-Resistance	$R_{DS(ON)}$	$V_{GS}=10V, I_D=1.5A$		0.72	0.9	$\Omega$
Gate Resistance	$R_G$	$f=1MHz, \text{Open Drain}$		6.0		$\Omega$
<b>Dynamic Characteristics</b>						
Input Capacitance	$C_{ISS}$	$V_{DS}=50V, V_{GS}=0V, f=1MHz$		296		pF
Output Capacitance	$C_{OSS}$			15		pF
Reverse Transfer Capacitance	$C_{RSS}$			0.4		
Effective output capacitance, energy related <sup>NOTE5</sup>	$C_{O(er)}$	$V_{GS}=0V, V_{DS}=0\dots 400V$		8.6		pF
Effective output capacitance, time related <sup>NOTE6</sup>	$C_{O(tr)}$			56.4		
Turn-on Delay Time	$t_{d(on)}$	$V_{DD}=400V, I_D=16A, R_G=5.3\Omega, V_{GS}=10V$		6		ns
Rise Time	$t_r$			5		
Turn-off Delay Time	$t_{d(off)}$			40		
Fall Time	$t_f$			13		
<b>Gate Charge Characteristics</b>						
Gate to Source Charge	$Q_{gs}$	$V_{DD}=480V, I_D=1.5A, V_{GS}=0 \text{ to } 10V$		1.6		nC
Gate to Drain Charge	$Q_{gd}$			2.2		
Gate Charge Total	$Q_g$			6.2		
Gate Plateau Voltage	$V_{plateau}$			5.2		V
<b>Reverse Diode Characteristics</b>						
Drain-Source Diode Forward Voltage	$V_{SD}$	$V_{GS}=0V, I_{SD}=1.5A$		0.82	1.1	V
Reverse Recovery Time	$t_{rr}$	$V_R=100V, I_F=1.5A, dI_F/dt=100A/\mu s$		110		ns
Reverse Recovery Charge	$Q_{rr}$			0.45		$\mu C$
Peak Reverse Recovery Current	$I_{rrm}$			8.2		A

Note:

 5.  $C_{O(er)}$  is a fixed capacitance that gives the same stored energy as  $C_{OSS}$  while  $V_{DS}$  is rising from 0 to 400V

 6.  $C_{O(tr)}$  is a fixed capacitance that gives the same charging time as  $C_{OSS}$  while  $V_{DS}$  is rising from 0 to 400 V



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